

## IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant(s):

David Albert Zoba

Assignee:

Amkor Technology, Inc.

Title:

STRUCTURES FOR IMPROVING HEAT DISSIPATION IN

STACKED SEMICONDUCTOR PACKAGES

Serial No.:

10/771,072

Filed:

February 2, 2004

Examiner:

Sheila V. Clark

Group Art Unit:

2815

Docket No.:

G007801

Chandler, AZ

Commissioner for Patents P.O. Box 1450 Alexandria, VA 22313-1450

## REVOCATION AND SUBSTITUTION OF POWER OF ATTORNEY UNDER 37 C.F.R. §1.36

sir:

Pursuant to 37 C.F.R. §1.36, Amkor Technology, Inc., the record owner of the above-identified patent application, revokes all previous powers of attorney and hereby appoints the following attorneys and/or agents assigned to the below Customer Number to prosecute this application and transact all business in the U.S. Patent and Trademark Office connected therewith:

## Customer Number 23513

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SERIAL NO. 10/771,072

EXHIBITC

The undersigned representative of the above-identified assignee certifies that the above-identified assignee is the assignee of the entire right, title and interest in the above-identified patent application by virtue of a chain of title from the inventor(s) of the above-identified patent application to the above-identified assignee.

An Assignment from the <u>inventor(s)</u> of the patent application to <u>Amkor Technology</u>. Inc. was recorded in the U.S. Patent and Trademark Office at Reel/Frame 012380/0068.

The undersigned (whose title is supplied below) is empowered to sign this certificate on behalf of the above-identified assignee.

Signature:

Name:

Paul W. Davis

Title: Vic

Vice President of Intellectual Property Law

11 Dawl Date: 10/2014

Amkor Technology, Inc.